

IN THE CLAIMS

Please revise the claims as follows:

1-11. (Cancelled)

12. (Presently amended) A semiconductor package, comprising:

a relatively thin substrate epoxy attached to a packaging substrate:

a relatively thick semiconductor epoxy attached to a semiconductor, the substrate epoxy and the semiconductor epoxy being made of the same epoxy, wherein said relatively thin substrate epoxy and said relatively thick semiconductor epoxy are attached to one another forming a stack including said packaging substrate, said relatively thin substrate epoxy, said relatively thick semiconductor epoxy, and said semiconductor; and

a housing enclosing said stack.

13. (Original) The semiconductor package of claim 12 wherein said relatively thick semiconductor epoxy is approximately 2.5 times or more as thick as said relatively thin substrate epoxy.

14. (Original) The semiconductor package of claim 12 wherein said relatively thick semiconductor epoxy is approximately 5 mils or more.

15. (Original) The semiconductor package of claim 12 wherein said relatively thin substrate epoxy is approximately 2 mils or less.

16. (Original) The semiconductor package of claim 12 wherein said packaging substrate is a lead frame.

17. (New) A semiconductor package, comprising:

a relatively thin substrate epoxy attached to a packaging substrate;

a relatively thick semiconductor epoxy having a thickness of approximately 5 mils or more attached to a semiconductor, wherein said relatively thin substrate epoxy and said relatively thick semiconductor epoxy are attached to one another forming a stack including said packaging substrate, said relatively thin substrate epoxy, said relatively thick semiconductor epoxy, and said semiconductor; and

a housing enclosing said stack.

18. (New) The semiconductor package of claim 17 wherein said relatively thick semiconductor epoxy is approximately 2.5 times or more as thick as said relatively thin substrate epoxy.

19. (New) The semiconductor package of claim 17 wherein said relatively thin substrate epoxy is approximately 2 mils or less.

20. (New) The semiconductor package of claim 17 wherein said packaging substrate is a lead frame.